

"Circuits and Systems for Sustainable Development"

# ISCAS 2024



Singapore | May 19-22, 2024

Resorts World Sentosa Convention Centre

## Call for Papers

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world's premier forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS 2024 will be held in Singapore, from May 19 to 22, 2024. ISCAS 2024 is inspired by the theme **"Circuits and Systems for Sustainable Development"**, which is perfectly aligned with the host city Singapore's goal. This symposium will include technical oral lectures and poster sessions, special sessions, tutorials, live demonstrations and workshops, ranging from various topics in circuits and systems.

**To implement the above vision, this year's conference will highlight the following innovation themes:**

- *Artificial Intelligence and Deep Learning*
- *Smart Systems for Automotive*
- *Brain: Innovation Neurotechnologies*
- *Intelligent Cyber Security Systems*
- *Food Security and Climate Change*
- *Ultra Low Power Circuits and Systems*

**Collecting contributions in areas of Circuits and Systems, including but not limited to:**

- Analog and Mixed Signal Circuits and Systems
- Digital Integrated Circuits and Systems
- Power and Energy Circuits and Systems
- Sensory Circuits and Systems
- Nonlinear Systems and Circuit Theory
- Digital Signal Processing
- Multimedia Systems and Applications
- Communications Circuits and Systems
- Biomedical Circuits and Systems
- Neural Networks and Neuromorphic Engineering
- Beyond CMOS: Nanoelectronics and Heterogeneous System Integration
- Education in Circuits and Systems
- Electronic Design Automation

### Special Initiatives of ISCAS 2024:

- **Emerging Technologies Workshops**  
On *Information Security*, *Climate Change*, and *GeronCAS*.
- **Cross-Society Special Sessions**  
Co-organized by CASS and other IEEE societies/councils, on recent attractive themes for cross-disciplinary collaboration.
- **Special Sections in IEEE Transactions**  
Selected papers will be invited for possible publications in: IEEE Trans. on Circuits and Systems – Part I, IEEE Trans. on Circuits and Systems – Part II, and IEEE Trans. on Biomedical Circuits and Systems.

### Important Dates:

|                                         |                        |
|-----------------------------------------|------------------------|
| Special Sessions Proposal:              | Oct 1, 2023 (extended) |
| Special Sessions Proposal Notification: | Oct 7, 2023 (extended) |
| Special Session Papers Submission:      | Oct 15, 2023           |
| Regular Papers Submission:              | Oct 15, 2023           |
| Tutorials Proposal:                     | Oct 15, 2023           |
| Live Demos Submission:                  | Oct 15, 2023           |
| All Authors' Decision Notification:     | Jan 15, 2024           |



[2024.ieee-iscas.org](https://2024.ieee-iscas.org)

## Organizing Committee

### General Chair

Amara Amara, Terre des hommes, Switzerland  
Yong Lian, York Univ., Canada  
Bah-Hwee Gwee, NTU, Singapore

### TPC Chair

Yoshifumi Nishio, Tokushima Univ., Japan  
Victor Grimblatt, Synopsys, Chile  
Nam Ling, Santa Clara Univ., USA

### Tutorial Chair

Massimo Alioto, NUS, Singapore  
Elena Blokhina, Univ. College Dublin, Ireland  
Francois Rivet, Univ. of Bordeaux, France

### Special Session Chair

Mohamad Sawan, Westlake Univ., China  
Volkan Kursun, Bilkent Univ., Turkey  
Nathalie Deltime, Univ. of Bordeaux, France

### Cross-Soc. Special Session Chair

Xinmiao Zhang, OSU, USA

### Embedded Workshop Chair

Fakhrul Zaman Rokhani, UPM, Malaysia

### Women in CAS (WiCAS) Program Chair

Yoko Uwate, Tokushima Univ., Japan

Maria Trocan, ISEP, France

### Young Professional (YP) Program Chair

Fidel Makatia, Autodesk, Kenya

### Live Demonstrations Chair

Chao Wang, Huazhong UST, China

Deruo Cheng, NTU, Singapore

### Publicity Chair

Zhiping Lin, NTU, Singapore  
Yajun Ha, Shanghai Tech Univ., China  
Nicole McFarlane, Univ. of Tennessee, USA  
Wei Liu, Queen Mary Univ. of London, UK

### International Liaison Chair

Franco Maloberti, Univ. of Parma, Italy  
Myung Hoon Sunwoo, Ajou Univ., South Korea  
Ricardo Reis, UFRGS, Brazil  
Jose Silva-Martinez, Texas A&M Univ., USA  
Wei Chen, Fudan Univ., China

### Publication Chair

Yongfu Li, Shanghai Jiao Tong Univ., China  
Kwen Siong Chong, Zero-Error Sys, Singapore

### Finance Chair

Saihua Xu, NTU, Singapore  
Tong Ge, NTU, Singapore

### Local Arrangement Chair

Jun Wei Lee, DSO, Singapore  
Kian Ann Ng, Digipen, Singapore  
Qinglai Liu, NTU, Singapore

### Sponsorship/Exhibition Chair

Xuanyao Fong, NUS, Singapore  
Anh Tuan Do, A\*STAR, Singapore  
Zhengguo Li, A\*STAR, Singapore

### Industry Liaison Chair

Kiran Gunnam, Western Digital, USA  
Yi Wang, Continental Automotive, Singapore  
Rajiv Joshi, IBM, USA  
Preet Yadav, NXP Semiconductors, India  
Yuanjin Zheng, NTU, Singapore

### Webmaster

Fan Yang, Qualcomm, Singapore

### Professional Conference Organizer

Stanley Teng, A\*Tenga C.E., Singapore  
Mary Teng, A\*Tenga C.E., Singapore